

February 1998 - Revised October 2003

## High-Speed CMOS Logic 12-Stage Binary Counter

### Features

- Fully Static Operation
- Buffered Inputs
- Common Reset
- Negative Edge Pulsing
- Fanout (Over Temperature Range)
  - Standard Outputs . . . . . 10 LSTTL Loads
  - Bus Driver Outputs . . . . . 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$  of  $V_{CC}$  at  $V_{CC} = 5V$
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,  $V_{IL} = 0.8V$  (Max),  $V_{IH} = 2V$  (Min)
  - CMOS Input Compatibility,  $I_I \leq 1\mu A$  at  $V_{OL}$ ,  $V_{OH}$

### Description

The 'HC4040 and 'HCT4040 are 14-stage ripple-carry binary counters. All counter stages are master-slave flip-flops. The state of the stage advances one count on the negative clock transition of each input pulse; a high voltage level on the MR line resets all counters to their zero state. All inputs and outputs are buffered.

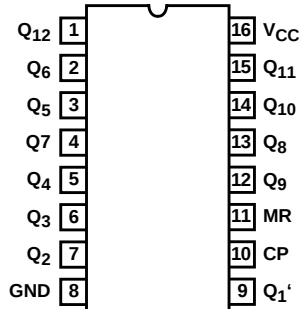
### Ordering Information

| PART NUMBER    | TEMP. RANGE (°C) | PACKAGE      |
|----------------|------------------|--------------|
| CD54HC4040F3A  | -55 to 125       | 16 Ld CERDIP |
| CD54HCT4040F3A | -55 to 125       | 16 Ld CERDIP |
| CD74HC4040E    | -55 to 125       | 16 Ld PDIP   |
| CD74HC4040M    | -55 to 125       | 16 Ld SOIC   |
| CD74HC4040MT   | -55 to 125       | 16 Ld SOIC   |
| CD74HC4040M96  | -55 to 125       | 16 Ld SOIC   |
| CD74HC4040NSR  | -55 to 125       | 16 Ld SOP    |
| CD74HCT4040E   | -55 to 125       | 16 Ld PDIP   |
| CD74HCT4040M   | -55 to 125       | 16 Ld SOIC   |
| CD74HCT4040MT  | -55 to 125       | 16 Ld SOIC   |
| CD74HCT4040M96 | -55 to 125       | 16 Ld SOIC   |

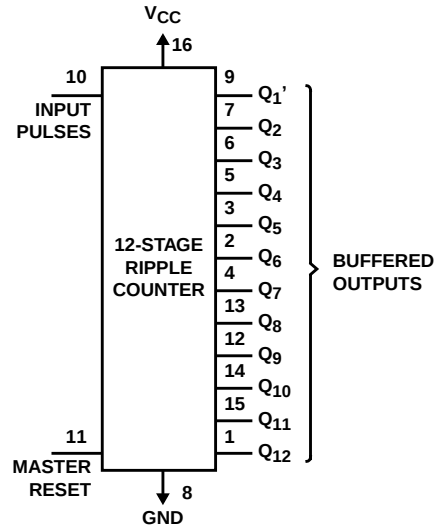
NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

### Pinout

CD54HC4040, CD54HCT4040  
(CERDIP)  
CD74HC4040  
(PDIP, SOIC, SOP)  
CD74HCT4040  
(PDIP, SOIC)  
TOP VIEW



## Functional Diagram

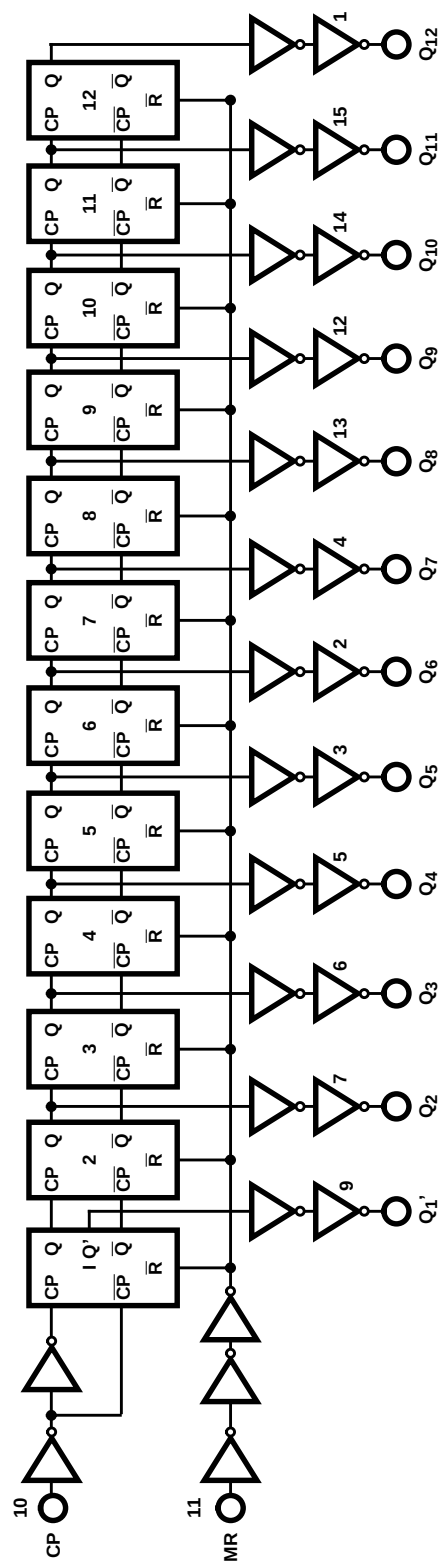


TRUTH TABLE

| CP COUNT | MR | OUTPUT STATE          |
|----------|----|-----------------------|
| ↑        | L  | No Change             |
| ↓        | L  | Advance to Next State |
| X        | H  | All Outputs Are Low   |

H = High Voltage Level, L = Low Voltage Level, X = Don't Care,  
 ↑ = Transition from Low to High Level, ↓ = Transition from High to Low.

## Logic Diagram



# CD54HC4040, CD74HC4040, CD54HCT4040, CD74HCT4040

## Absolute Maximum Ratings

DC Supply Voltage,  $V_{CC}$  ..... -0.5V to 7V  
 DC Input Diode Current,  $I_{IK}$   
 For  $V_I < -0.5V$  or  $V_I > V_{CC} + 0.5V$  .....  $\pm 20mA$   
 DC Output Diode Current,  $I_{OK}$   
 For  $V_O < -0.5V$  or  $V_O > V_{CC} + 0.5V$  .....  $\pm 20mA$   
 DC Output Source or Sink Current per Output Pin,  $I_O$   
 For  $V_O > -0.5V$  or  $V_O < V_{CC} + 0.5V$  .....  $\pm 25mA$   
 DC  $V_{CC}$  or Ground Current,  $I_{CC}$  .....  $\pm 50mA$

## Thermal Information

Package Thermal Impedance,  $\theta_{JA}$  (see Note 1):  
 E (PDIP) Package .....  $67^{\circ}C/W$   
 M (SOIC) Package .....  $73^{\circ}C/W$   
 NS (SOP) Package .....  $64^{\circ}C/W$   
 Maximum Junction Temperature .....  $150^{\circ}C$   
 Maximum Storage Temperature Range .....  $-65^{\circ}C$  to  $150^{\circ}C$   
 Maximum Lead Temperature (Soldering 10s) .....  $300^{\circ}C$   
 (SOIC - Lead Tips Only)

## Operating Conditions

Temperature Range ( $T_A$ ) .....  $-55^{\circ}C$  to  $125^{\circ}C$   
 Supply Voltage Range,  $V_{CC}$   
 HC Types ..... 2V to 6V  
 HCT Types ..... 4.5V to 5.5V  
 DC Input or Output Voltage,  $V_I$ ,  $V_O$  ..... 0V to  $V_{CC}$   
 Input Rise and Fall Time  
 2V ..... 1000ns (Max)  
 4.5V ..... 500ns (Max)  
 6V ..... 400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

## DC Electrical Specifications

| PARAMETER                               | SYMBOL          | TEST CONDITIONS                    |                     | V <sub>CC</sub> (V) | 25°C |     |      | -40°C TO 85°C |      | -55°C TO 125°C |      | UNITS |
|-----------------------------------------|-----------------|------------------------------------|---------------------|---------------------|------|-----|------|---------------|------|----------------|------|-------|
|                                         |                 | V <sub>I</sub> (V)                 | I <sub>O</sub> (mA) |                     | MIN  | TYP | MAX  | MIN           | MAX  | MIN            | MAX  |       |
| HC TYPES                                |                 |                                    |                     |                     |      |     |      |               |      |                |      |       |
| High Level Input Voltage                | V <sub>IH</sub> | -                                  | -                   | 2                   | 1.5  | -   | -    | 1.5           | -    | 1.5            | -    | V     |
|                                         |                 |                                    |                     | 4.5                 | 3.15 | -   | -    | 3.15          | -    | 3.15           | -    | V     |
|                                         |                 |                                    |                     | 6                   | 4.2  | -   | -    | 4.2           | -    | 4.2            | -    | V     |
| Low Level Input Voltage                 | V <sub>IL</sub> | -                                  | -                   | 2                   | -    | -   | 0.5  | -             | 0.5  | -              | 0.5  | V     |
|                                         |                 |                                    |                     | 4.5                 | -    | -   | 1.35 | -             | 1.35 | -              | 1.35 | V     |
|                                         |                 |                                    |                     | 6                   | -    | -   | 1.8  | -             | 1.8  | -              | 1.8  | V     |
| High Level Output Voltage<br>CMOS Loads | V <sub>OH</sub> | V <sub>IH</sub> or V <sub>IL</sub> | -0.02               | 2                   | 1.9  | -   | -    | 1.9           | -    | 1.9            | -    | V     |
|                                         |                 |                                    | -0.02               | 4.5                 | 4.4  | -   | -    | 4.4           | -    | 4.4            | -    | V     |
|                                         |                 |                                    | -0.02               | 6                   | 5.9  | -   | -    | 5.9           | -    | 5.9            | -    | V     |
| High Level Output Voltage<br>TTL Loads  |                 |                                    | -                   | -                   | -    | -   | -    | -             | -    | -              | -    | V     |
|                                         |                 |                                    | -4                  | 4.5                 | 3.98 | -   | -    | 3.84          | -    | 3.7            | -    | V     |
|                                         |                 |                                    | -5.2                | 6                   | 5.48 | -   | -    | 5.34          | -    | 5.2            | -    | V     |
| Low Level Output Voltage<br>CMOS Loads  | V <sub>OL</sub> | V <sub>IH</sub> or V <sub>IL</sub> | 0.02                | 2                   | -    | -   | 0.1  | -             | 0.1  | -              | 0.1  | V     |
|                                         |                 |                                    | 0.02                | 4.5                 | -    | -   | 0.1  | -             | 0.1  | -              | 0.1  | V     |
|                                         |                 |                                    | 0.02                | 6                   | -    | -   | 0.1  | -             | 0.1  | -              | 0.1  | V     |
| Low Level Output Voltage<br>TTL Loads   |                 |                                    | -                   | -                   | -    | -   | -    | -             | -    | -              | -    | V     |
|                                         |                 |                                    | 4                   | 4.5                 | -    | -   | 0.26 | -             | 0.33 | -              | 0.4  | V     |
|                                         |                 |                                    | 5.2                 | 6                   | -    | -   | 0.26 | -             | 0.33 | -              | 0.4  | V     |
| Input Leakage Current                   | I <sub>I</sub>  | V <sub>CC</sub> or GND             | -                   | 6                   | -    | -   | ±0.1 | -             | ±1   | -              | ±1   | μA    |
| Quiescent Device Current                | I <sub>CC</sub> | V <sub>CC</sub> or GND             | 0                   | 6                   | -    | -   | 8    | -             | 80   | -              | 160  | μA    |

**CD54HC4040, CD74HC4040, CD54HCT4040, CD74HCT4040**

**DC Electrical Specifications (Continued)**

| PARAMETER                                                         | SYMBOL                       | TEST CONDITIONS                    |                     | V <sub>CC</sub> (V) | 25°C |     |      | -40°C TO 85°C |      | -55°C TO 125°C |     | UNITS |
|-------------------------------------------------------------------|------------------------------|------------------------------------|---------------------|---------------------|------|-----|------|---------------|------|----------------|-----|-------|
|                                                                   |                              | V <sub>I</sub> (V)                 | I <sub>O</sub> (mA) |                     | MIN  | TYP | MAX  | MIN           | MAX  | MIN            | MAX |       |
| HCT TYPES                                                         |                              |                                    |                     |                     |      |     |      |               |      |                |     |       |
| High Level Input Voltage                                          | V <sub>IH</sub>              | -                                  | -                   | 4.5 to 5.5          | 2    | -   | -    | 2             | -    | 2              | -   | V     |
| Low Level Input Voltage                                           | V <sub>IL</sub>              | -                                  | -                   | 4.5 to 5.5          | -    | -   | 0.8  | -             | 0.8  | -              | 0.8 | V     |
| High Level Output Voltage<br>CMOS Loads                           | V <sub>OH</sub>              | V <sub>IH</sub> or V <sub>IL</sub> | -0.02               | 4.5                 | 4.4  | -   | -    | 4.4           | -    | 4.4            | -   | V     |
| High Level Output Voltage<br>TTL Loads                            |                              |                                    | -4                  | 4.5                 | 3.98 | -   | -    | 3.84          | -    | 3.7            | -   | V     |
| Low Level Output Voltage<br>CMOS Loads                            | V <sub>OL</sub>              | V <sub>IH</sub> or V <sub>IL</sub> | 0.02                | 4.5                 | -    | -   | 0.1  | -             | 0.1  | -              | 0.1 | V     |
| Low Level Output Voltage<br>TTL Loads                             |                              |                                    | 4                   | 4.5                 | -    | -   | 0.26 | -             | 0.33 | -              | 0.4 | V     |
| Input Leakage Current                                             | I <sub>I</sub>               | V <sub>CC</sub> and GND            | 0                   | 5.5                 | -    | -   | ±0.1 | -             | ±1   | -              | ±1  | μA    |
| Quiescent Device Current                                          | I <sub>CC</sub>              | V <sub>CC</sub> or GND             | 0                   | 5.5                 | -    | -   | 8    | -             | 80   | -              | 160 | μA    |
| Additional Quiescent Device Current<br>Per Input Pin: 1 Unit Load | ΔI <sub>CC</sub><br>(Note 2) | V <sub>CC</sub><br>-2.1            | -                   | 4.5 to 5.5          | -    | 100 | 360  | -             | 450  | -              | 490 | μA    |

NOTE:

- For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

**HCT Input Loading Table**

| INPUT | UNIT LOADS |
|-------|------------|
| MR    | 0.65       |
| CP    | 0.5        |

NOTE: Unit Load is ΔI<sub>CC</sub> limit specified in DC Electrical Table, e.g., 360μA max at 25°C.

**Prerequisite for Switching Specifications**

| PARAMETER                     | SYMBOL           | V <sub>CC</sub> (V) | 25°C |     | -40°C TO 85°C |     | -55°C TO 125°C |     | UNITS |
|-------------------------------|------------------|---------------------|------|-----|---------------|-----|----------------|-----|-------|
|                               |                  |                     | MIN  | MAX | MIN           | MAX | MIN            | MAX |       |
| HC TYPES                      |                  |                     |      |     |               |     |                |     |       |
| Maximum Input Pulse Frequency | f <sub>MAX</sub> | 2                   | 6    | -   | 5             | -   | 4              | -   | MHz   |
|                               |                  | 4.5                 | 30   | -   | 25            | -   | 20             | -   | MHz   |
|                               |                  | 6                   | 35   | -   | 29            | -   | 24             | -   | MHz   |
| Input Pulse Width             | t <sub>W</sub>   | 2                   | 80   | -   | 100           | -   | 120            | -   | ns    |
|                               |                  | 4.5                 | 16   | -   | 20            | -   | 24             | -   | ns    |
|                               |                  | 6                   | 14   | -   | 17            | -   | 20             | -   | ns    |

**CD54HC4040, CD74HC4040, CD54HCT4040, CD74HCT4040**

**Prerequisite for Switching Specifications (Continued)**

| PARAMETER                     | SYMBOL           | V <sub>CC</sub> (V) | 25°C |     | -40°C TO 85°C |     | -55°C TO 125°C |     | UNITS |
|-------------------------------|------------------|---------------------|------|-----|---------------|-----|----------------|-----|-------|
|                               |                  |                     | MIN  | MAX | MIN           | MAX | MIN            | MAX |       |
| Reset Removal Time            | t <sub>REM</sub> | 2                   | 50   | -   | 65            | -   | 75             | -   | ns    |
|                               |                  | 4.5                 | 10   | -   | 13            | -   | 15             | -   | ns    |
|                               |                  | 6                   | 9    | -   | 11            | -   | 13             | -   | ns    |
| Reset Pulse Width             | t <sub>W</sub>   | 2                   | 80   | -   | 100           | -   | 120            | -   | ns    |
|                               |                  | 4.5                 | 16   | -   | 20            | -   | 24             | -   | ns    |
|                               |                  | 6                   | 14   | -   | 17            | -   | 20             | -   | ns    |
| HCT TYPES                     |                  |                     |      |     |               |     |                |     |       |
| Maximum Input Pulse Frequency | f <sub>MAX</sub> | 4.5                 | 25   | -   | 20            | -   | 16             | -   | MHz   |
| Input Pulse Width             | t <sub>W</sub>   | 4.5                 | 20   | -   | 25            | -   | 30             | -   | ns    |
| Reset Recovery Time           | t <sub>REM</sub> | 4.5                 | 10   | -   | 13            | -   | 15             | -   | ns    |
| Reset Pulse Width             | t <sub>W</sub>   | 4.5                 | 20   | -   | 25            | -   | 30             | -   | ns    |

**Switching Specifications** Input t<sub>r</sub>, t<sub>f</sub> = 6ns

| PARAMETER                                                            | SYMBOL                              | TEST CONDITIONS       | V <sub>CC</sub> (V) | 25°C |     |     | -40°C TO 85°C |     | -55°C TO 125°C |     | UNITS |
|----------------------------------------------------------------------|-------------------------------------|-----------------------|---------------------|------|-----|-----|---------------|-----|----------------|-----|-------|
|                                                                      |                                     |                       |                     | MIN  | TYP | MAX | MIN           | MAX | MIN            | MAX |       |
| HC TYPES                                                             |                                     |                       |                     |      |     |     |               |     |                |     |       |
| Propagation Delay<br>(Figure 1)<br><br>CP to Q <sub>1</sub> ' Output | t <sub>PLH</sub> , t <sub>PHL</sub> | C <sub>L</sub> = 50pF | 2                   | -    | -   | 140 | -             | 175 | -              | 210 | ns    |
|                                                                      |                                     |                       | 4.5                 | -    | -   | 28  | -             | 35  | -              | 42  | ns    |
|                                                                      |                                     | C <sub>L</sub> =15pF  | 5                   | -    | 11  | -   | -             | -   | -              | -   | ns    |
|                                                                      |                                     | C <sub>L</sub> = 50pF | 6                   | -    | -   | 24  | -             | 30  | -              | 36  | ns    |
| Q <sub>n</sub> to Q <sub>n</sub> + 1                                 | t <sub>PLH</sub> , t <sub>PHL</sub> | C <sub>L</sub> = 50pF | 2                   | -    | -   | 75  | -             | 95  | -              | 110 | ns    |
|                                                                      |                                     |                       | 4.5                 | -    | -   | 15  | -             | 19  | -              | 22  | ns    |
|                                                                      |                                     | C <sub>L</sub> =15pF  | 5                   | -    | 4   | -   | -             | -   | -              | -   | ns    |
|                                                                      |                                     | C <sub>L</sub> = 50pF | 6                   | -    | -   | 13  | -             | 16  | -              | 19  | ns    |
| MR to Q <sub>n</sub>                                                 | t <sub>PLH</sub> , t <sub>PHL</sub> | C <sub>L</sub> = 50pF | 2                   | -    | -   | 170 | -             | 215 | -              | 255 | ns    |
|                                                                      |                                     |                       | 4.5                 | -    | -   | 34  | -             | 43  | -              | 51  | ns    |
|                                                                      |                                     |                       | 5                   | -    | 14  | -   | -             | -   | -              | -   | ns    |
|                                                                      |                                     |                       | 6                   | -    | -   | 29  | -             | 37  | -              | 43  | ns    |
| Output Transition Time<br>(Figure 1)                                 | t <sub>TLH</sub> , t <sub>THL</sub> | C <sub>L</sub> = 50pF | 2                   | -    | -   | 75  | -             | 95  | -              | 110 | ns    |
|                                                                      |                                     |                       | 4.5                 | -    | -   | 15  | -             | 19  | -              | 22  | ns    |
|                                                                      |                                     |                       | 6                   | -    | -   | 13  | -             | 16  | -              | 19  | ns    |
| Input Capacitance                                                    | C <sub>IN</sub>                     | C <sub>L</sub> = 50pF | -                   | -    | -   | 10  | -             | 10  | -              | 10  | pF    |
| Power Dissipation<br>Capacitance (Notes 3, 4)                        | C <sub>PD</sub>                     | C <sub>L</sub> =15pF  | 5                   | -    | 40  | -   | -             | -   | -              | -   | pF    |
| HCT TYPES                                                            |                                     |                       |                     |      |     |     |               |     |                |     |       |
| Propagation Delay<br>(Figure 1)<br><br>CP to Q <sub>1</sub> ' Output | t <sub>PLH</sub> , t <sub>PHL</sub> | C <sub>L</sub> = 50pF | 4.5                 | -    | -   | 40  | -             | 50  | -              | 60  | ns    |
|                                                                      |                                     | C <sub>L</sub> =15pF  | 5                   | -    | 17  | -   | -             | -   | -              | -   | ns    |

# CD54HC4040, CD74HC4040, CD54HCT4040, CD74HCT4040

## Switching Specifications Input $t_r, t_f = 6\text{ns}$ (Continued)

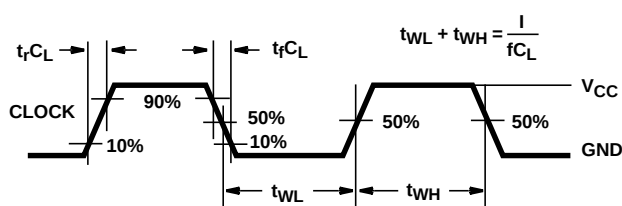
| PARAMETER                                  | SYMBOL             | TEST CONDITIONS     | $V_{CC}$ (V) | 25°C |     |     | -40°C TO 85°C |     | -55°C TO 125°C |     | UNITS |
|--------------------------------------------|--------------------|---------------------|--------------|------|-----|-----|---------------|-----|----------------|-----|-------|
|                                            |                    |                     |              | MIN  | TYP | MAX | MIN           | MAX | MIN            | MAX |       |
| $Q_n$ to $Q_{n+1}$                         | $t_{PLH}, t_{PHL}$ | $C_L = 50\text{pF}$ | 4.5          | -    | -   | 15  | -             | 19  | -              | 22  | ns    |
|                                            |                    | $C_L = 15\text{pF}$ | 5            | -    | 4   | -   | -             | -   | -              | -   | ns    |
| MR to $Q_n$                                | $t_{PLH}, t_{PHL}$ | $C_L = 50\text{pF}$ | 4.5          | -    | -   | 40  | -             | 50  | -              | 60  | ns    |
|                                            |                    | $C_L = 15\text{pF}$ | 5            | -    | 17  | -   | -             | -   | -              | -   | ns    |
| Output Transition                          | $t_{TLH}, t_{THL}$ | $C_L = 50\text{pF}$ | 4.5          | -    | -   | 15  | -             | 19  | -              | 22  | ns    |
| Input Capacitance                          | $C_{IN}$           | $C_L = 15\text{pF}$ | -            | -    | -   | 10  | -             | 10  | -              | 10  | pF    |
| Power Dissipation Capacitance (Notes 3, 4) | $C_{PD}$           | $C_L = 15\text{pF}$ | 5            | -    | 45  | -   | -             | -   | -              | -   | pF    |

NOTES:

3.  $C_{PD}$  is used to determine the dynamic power consumption, per package.

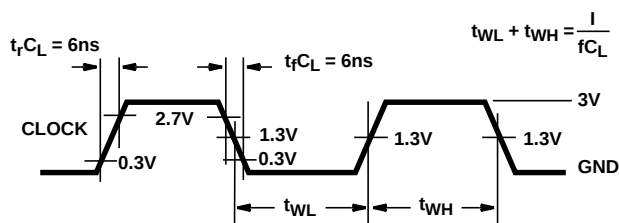
4.  $P_D = V_{CC}^2 f_i + \sum (C_L V_{CC}^2 f_i / M)$  where:  $M = 2^1, 2^2, 2^3, \dots, 2^{12}$ ,  $f_i$  = Input Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

## Test Circuits and Waveforms



NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

FIGURE 1. HC CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH



NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

FIGURE 2. HCT CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH

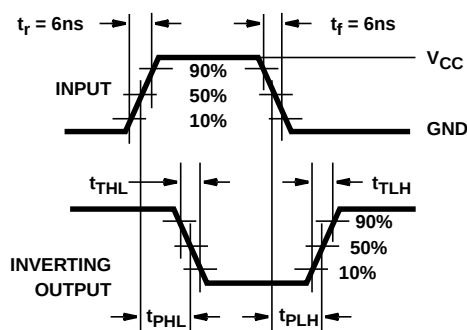


FIGURE 3. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

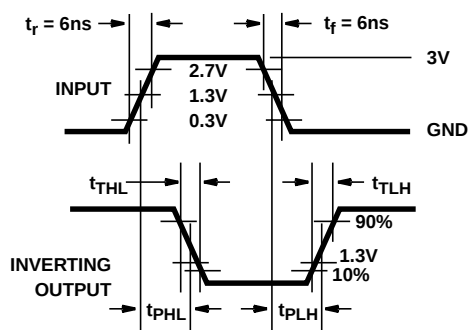
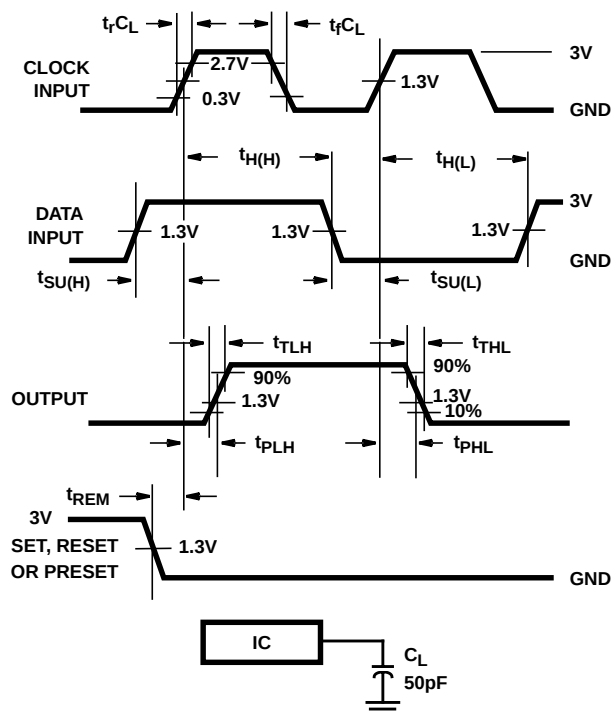


FIGURE 4. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC



**FIGURE 6. HCT SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS**

**PACKAGING INFORMATION**

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup>    | Lead/<br>Ball Finish | MSL Peak Temp <sup>(3)</sup> | Samples<br>(Requires Login) |
|------------------|-----------------------|--------------|-----------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| 5962-8994701MEA  | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                        | Call TI              | Call TI                      |                             |
| CD54HC4040F      | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| CD54HC4040F3A    | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| CD54HCT4040F3A   | ACTIVE                | CDIP         | J               | 16   | 1           | TBD                        | A42                  | N / A for Pkg Type           |                             |
| CD74HC4040E      | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD74HC4040EE4    | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD74HC4040M      | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC4040M96    | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC4040M96E4  | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC4040M96G4  | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC4040ME4    | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC4040MG4    | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC4040MT     | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC4040MTE4   | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HC4040MTG4   | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT4040E     | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD74HCT4040EE4   | ACTIVE                | PDIP         | N               | 16   | 25          | Pb-Free (RoHS)             | CU NIPDAU            | N / A for Pkg Type           |                             |
| CD74HCT4040M     | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT4040M96   | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT4040M96E4 | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS<br>& no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |

| Orderable Device | Status <sup>(1)</sup> | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <sup>(2)</sup> | Lead/<br>Ball Finish | MSL Peak Temp <sup>(3)</sup> | Samples<br>(Requires Login) |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|----------------------|------------------------------|-----------------------------|
| CD74HCT4040M96G4 | ACTIVE                | SOIC         | D               | 16   | 2500        | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT4040ME4   | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT4040MG4   | ACTIVE                | SOIC         | D               | 16   | 40          | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT4040MT    | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT4040MTE4  | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |
| CD74HCT4040MTG4  | ACTIVE                | SOIC         | D               | 16   | 250         | Green (RoHS & no Sb/Br) | CU NIPDAU            | Level-1-260C-UNLIM           |                             |

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**OTHER QUALIFIED VERSIONS OF CD54HC4040, CD54HCT4040, CD74HC4040, CD74HCT4040 :**

- Catalog: [CD74HC4040](#), [CD74HCT4040](#)
- Military: [CD54HC4040](#), [CD54HCT4040](#)

**NOTE: Qualified Version Definitions:**

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

| Device         | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD74HC4040M96  | SOIC         | D               | 16   | 2500 | 330.0              | 16.4               | 6.5     | 10.3    | 2.1     | 8.0     | 16.0   | Q1            |
| CD74HCT4040M96 | SOIC         | D               | 16   | 2500 | 330.0              | 16.4               | 6.5     | 10.3    | 2.1     | 8.0     | 16.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device         | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD74HC4040M96  | SOIC         | D               | 16   | 2500 | 333.2       | 345.9      | 28.6        |
| CD74HCT4040M96 | SOIC         | D               | 16   | 2500 | 333.2       | 345.9      | 28.6        |

J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



| PINS **<br>DIM | 14                     | 16                     | 18                     | 20                     |
|----------------|------------------------|------------------------|------------------------|------------------------|
| A              | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC | 0.300<br>(7,62)<br>BSC |
| B MAX          | 0.785<br>(19,94)       | .840<br>(21,34)        | 0.960<br>(24,38)       | 1.060<br>(26,92)       |
| B MIN          | —                      | —                      | —                      | —                      |
| C MAX          | 0.300<br>(7,62)        | 0.300<br>(7,62)        | 0.310<br>(7,87)        | 0.300<br>(7,62)        |
| C MIN          | 0.245<br>(6,22)        | 0.245<br>(6,22)        | 0.220<br>(5,59)        | 0.245<br>(6,22)        |



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



| PINS **             | 14               | 16               | 18               | 20               |
|---------------------|------------------|------------------|------------------|------------------|
| DIM                 |                  |                  |                  |                  |
| A MAX               | 0.775<br>(19,69) | 0.775<br>(19,69) | 0.920<br>(23,37) | 1.060<br>(26,92) |
| A MIN               | 0.745<br>(18,92) | 0.745<br>(18,92) | 0.850<br>(21,59) | 0.940<br>(23,88) |
| MS-001<br>VARIATION | AA               | BB               | AC               | AD               |



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

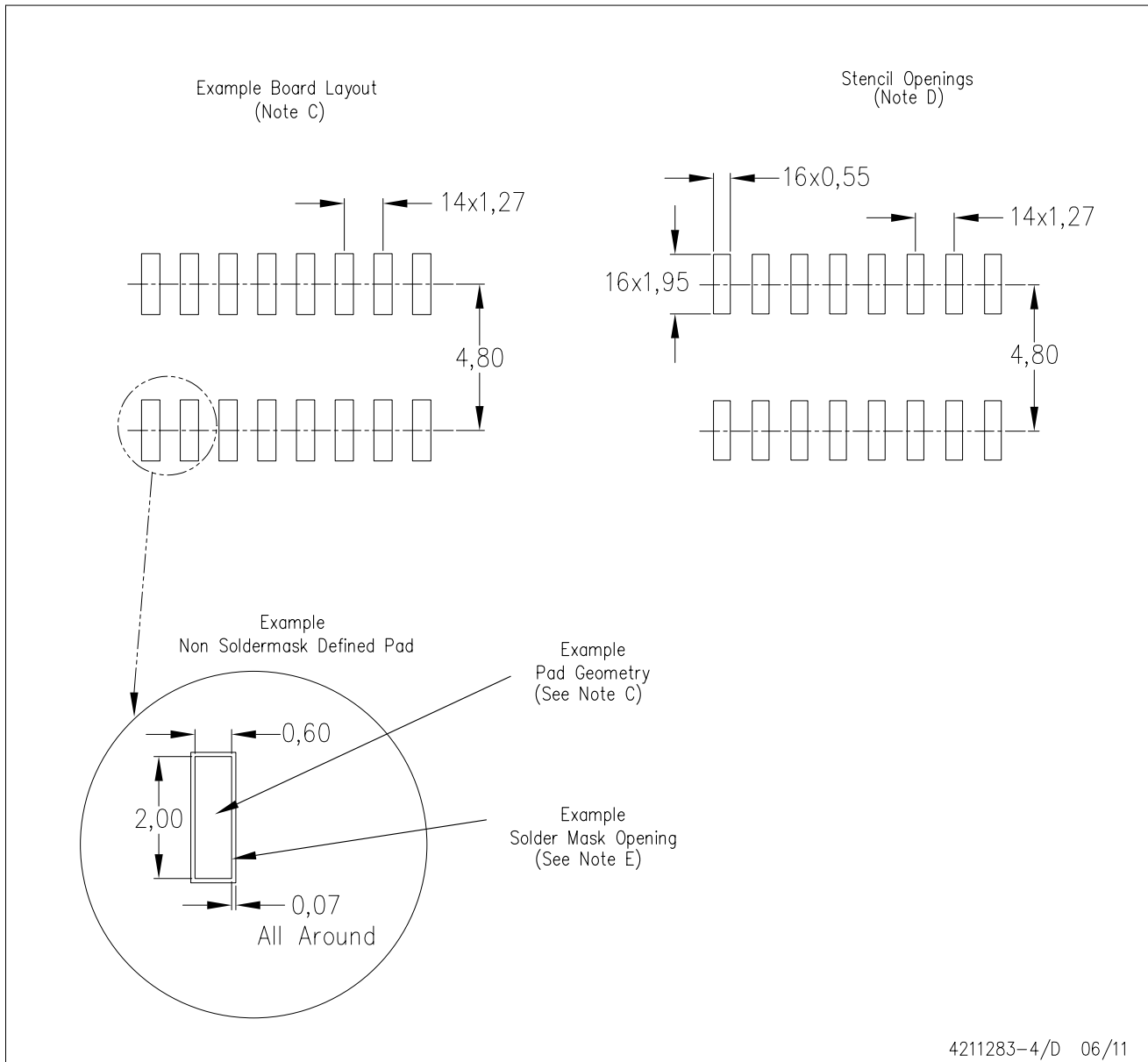


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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